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Intel® Celeron® Processor B815 (2M Cache, 1.60 GHz)

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PCN/MDDS Information

Specifications

Essentials

Status	Launched
Launch Date	Q1'12
Processor Number	B815
L3 Cache	2 MB
DMI	5 GT/s
Instruction Set	64-bit
Instruction Set Extensions	SSE4.x
Embedded Options Available	No
Lithography	32 nm
Recommended Customer Price	TRAY: \$86.00
Datasheet	Link

Performance

# of Cores	2
# of Threads	2
Processor Base Frequency	1.6 GHz
TDP	35 W

Memory Specifications

Max Memory Size (dependent on memory type)	16 GB
Memory Types	DDR3 1066/1333
Max # of Memory Channels	2
Max Memory Bandwidth	21.3 GB/s
ECC Memory Supported *	No

Graphics Specifications

Processor Graphics *	Intel® HD Graphics
Graphics Base Frequency	650 MHz
Graphics Max Dynamic Frequency	1.05 GHz
Graphics Output	eDP/DP/HDMI/SDVO/CRT
Intel® Quick Sync Video	No
Intel® InTru™ 3D Technology	No
Intel® Insider™	No
Intel® Wireless Display	No
Intel® Flexible Display Interface (Intel® FDI)	Yes
Intel® Clear Video HD Technology	No
Macrovision* License Required	No
# of Displays Supported *	2

Expansion Options

PCI Express Revision	2.0
PCI Express Configurations *	1x16, 2x8, 1x8 2x4
Max # of PCI Express Lanes	16

Package Specifications

Max CPU Configuration	1
T _{JUNCTION}	100C
Package Size	37.5mmx37.5mm (rPGA988B)
Graphics and IMC Lithography	32 nm
Sockets Supported	FCPGA988
Low Halogen Options Available	See MDDS

Advanced Technologies

Intel® Turbo Boost Technology *	No
Intel® vPro Technology *	No
Intel® Hyper-Threading Technology *	No
Intel® Virtualization Technology (VT-x) *	Yes
Intel® Virtualization Technology for Directed I/O (VT-d) *	No
Intel® 64 *	Yes
Intel® My WiFi Technology	No
4G WiMAX Wireless Technology	No
Idle States	Yes
Enhanced Intel SpeedStep® Technology	Yes
Intel® Demand Based Switching	No
Thermal Monitoring Technologies	Yes
Intel® Fast Memory Access	Yes
Intel® Flex Memory Access	Yes

Intel® Data Protection Technology

AES New Instructions	No
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Intel® Platform Protection Technology

Trusted Execution Technology *	No
Execute Disable Bit *	Yes
Anti-Theft Technology	No

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

* This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

See <http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading/hyper-threading-technology.html?wapkw=hyper+threading> for more information including details on which processors support Intel® HT Technology.

Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology. See www.intel.com/technology/turboboost/ for more information.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet J5-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

For benchmarking data see <http://www.intel.com/performance>.

Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. See <http://www.intel.com/content/www/us/en/processors/processor-numbers.html> for details.

Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS.

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